

#13/Drawing
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12/22/02
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kazuo MATSUZAKI, *et al.*

Group Art Unit: 2811

Serial No.: 09/756,686

Examiner: S. Loke

Filed: January 9, 2001

Attorney Docket No.: FUJI:179

For: SEMICONDUCTOR DEVICE EXHIBITING A HIGH BREAKDOWN VOLTAGE AND THE METHOD
OF MANUFACTURING THE SAMEAssistant Commissioner for Patents
Washington, D.C. 20231Certificate of Filing By Facsimile

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Trademark Office, Technology Center 2800, at telephone
number: 703-872-9318

Date: 12/10/02By: M. Rossi

Marc A. Rossi

PROPOSED DRAWING AMENDMENT

Sir:

Enclosed for the examiner's approval are copies of Figs. 1 and 3-24(b) with handwritten
markings showing the proposed changes, namely removing all extraneous reference descriptions
from these figures and including the legend "Prior Art" in Figs. 21, 22(a), 22(b), 23, and 24.

Respectfully submitted,

Date: 12/10/02M. Rossi
Marc A. Rossi

Registration No. 31,923

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P.O. Box 826
Ashburn, VA 20146-0826
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1/13

Fig. 1

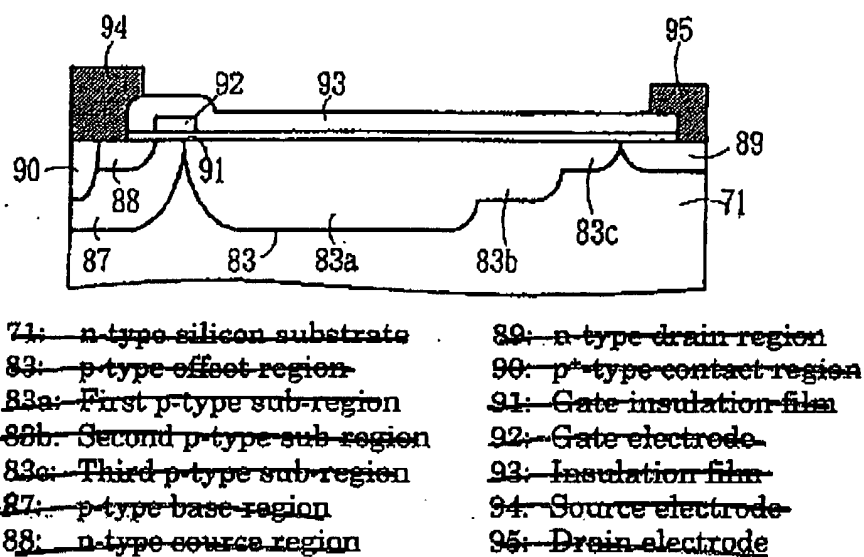
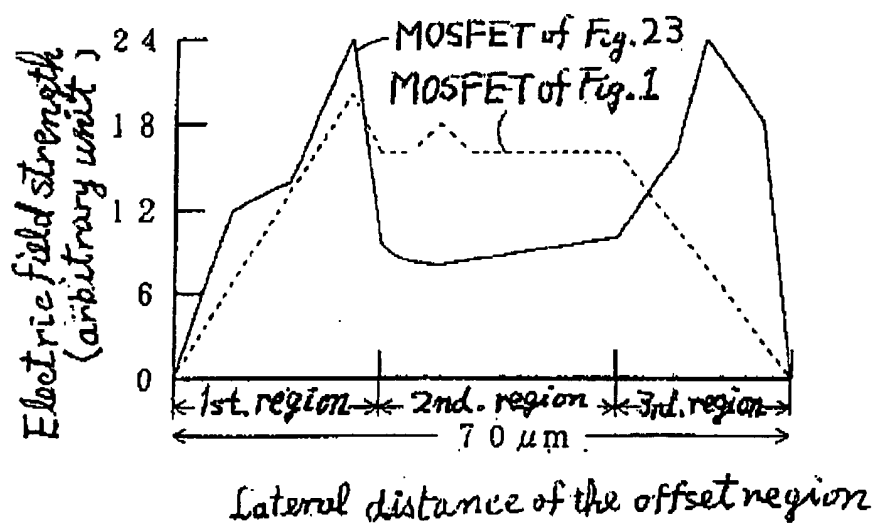


Fig. 2



2/13

Fig. 3

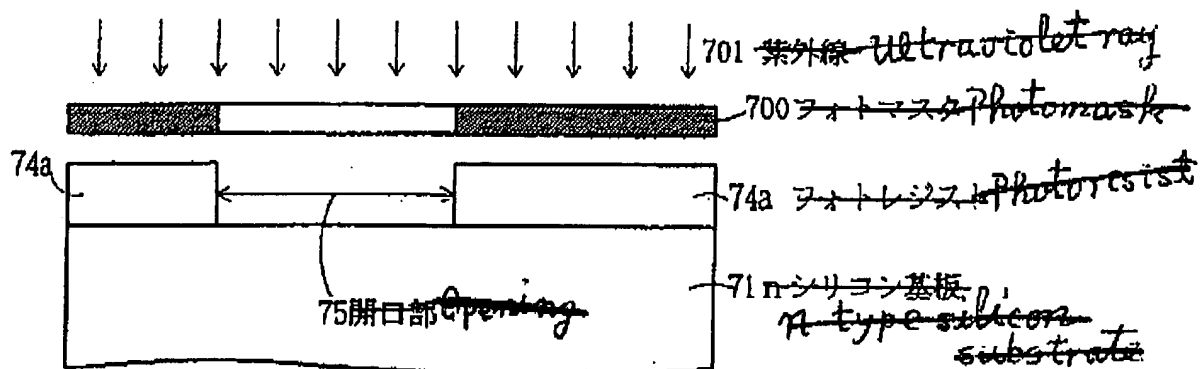


Fig. 4

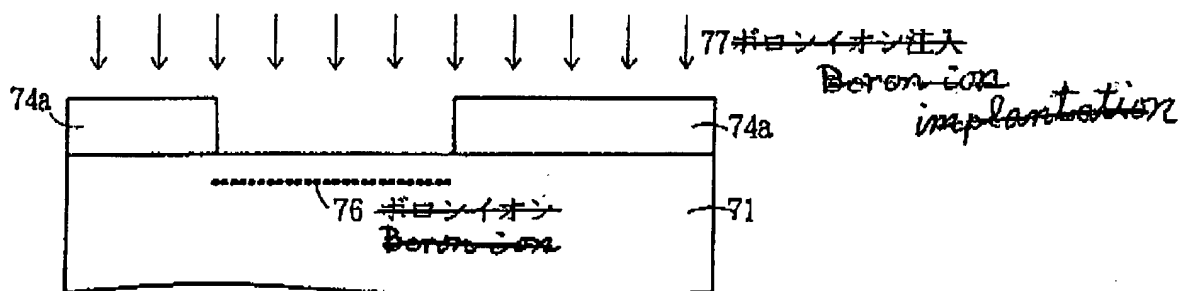
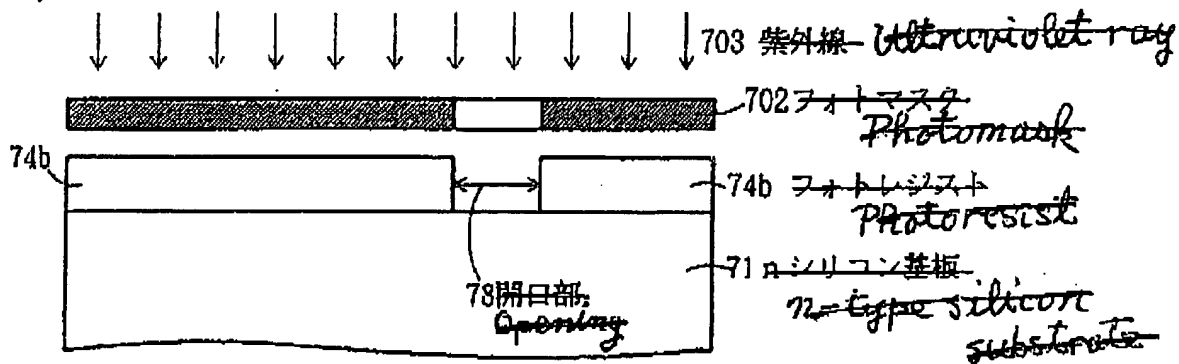


Fig. 5



2/13

Fig. 6

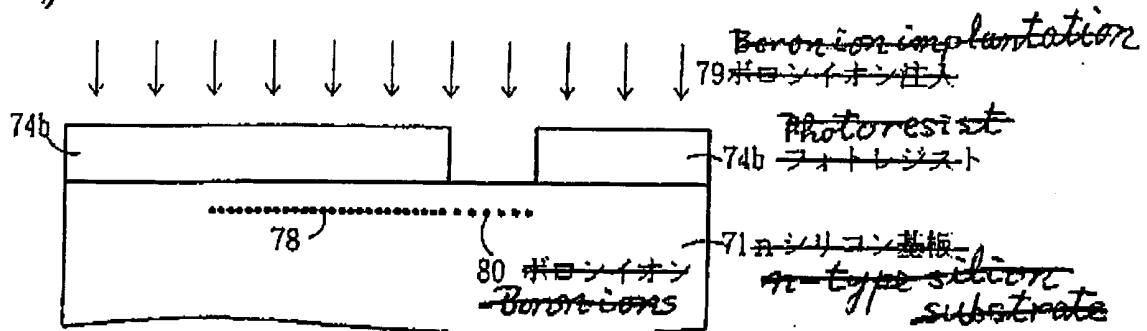


Fig. 7

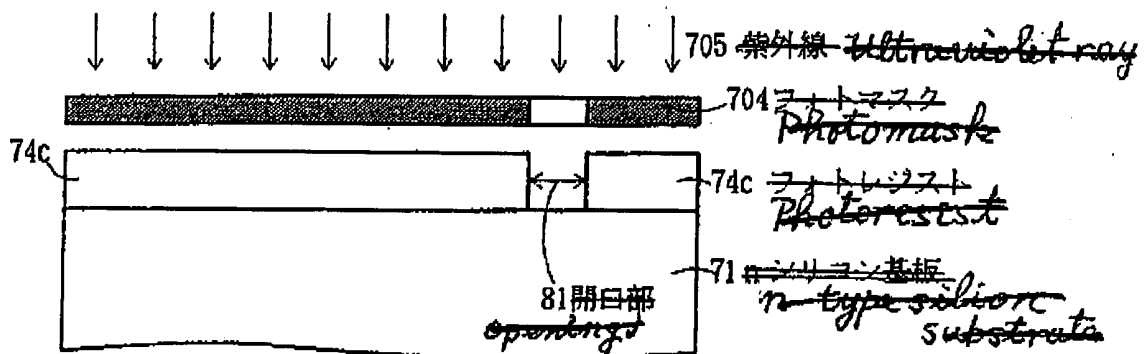


Fig. 8

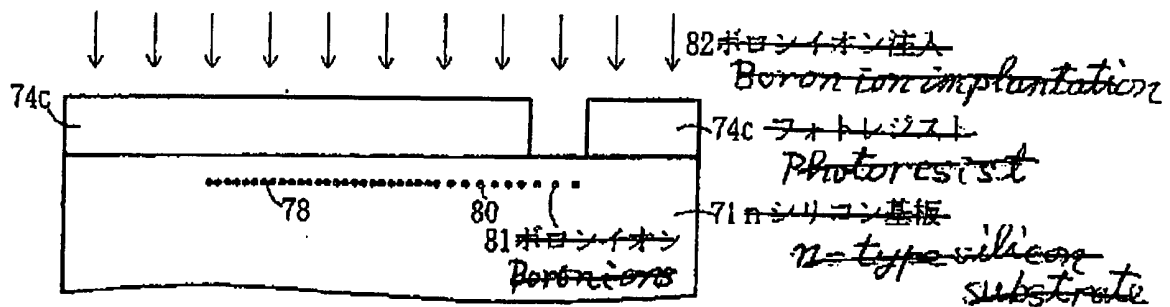


Fig. 9

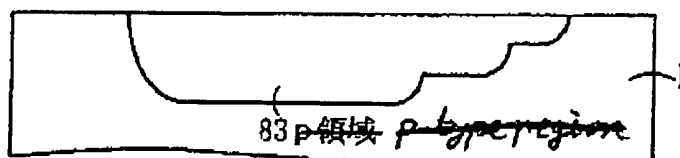


Fig. 10

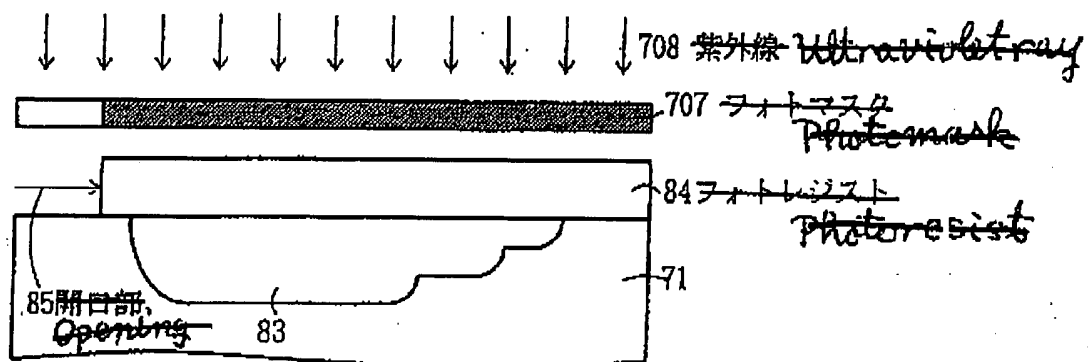


Fig. 11

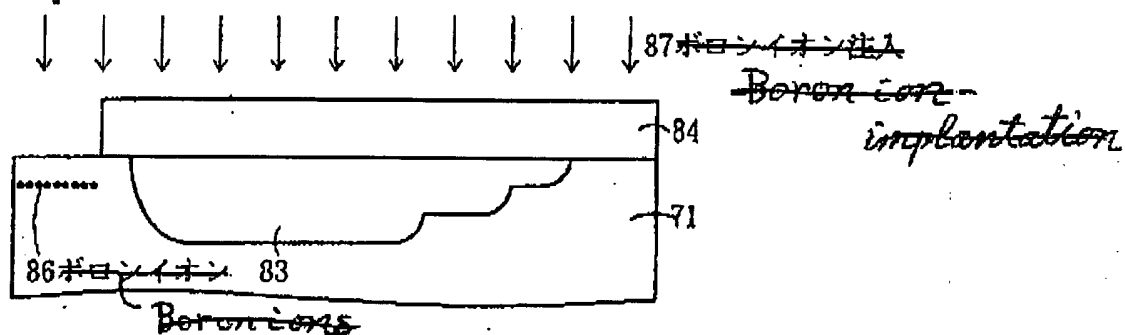
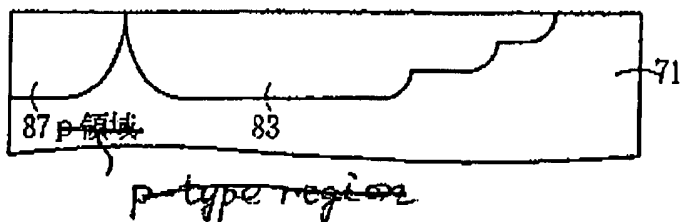
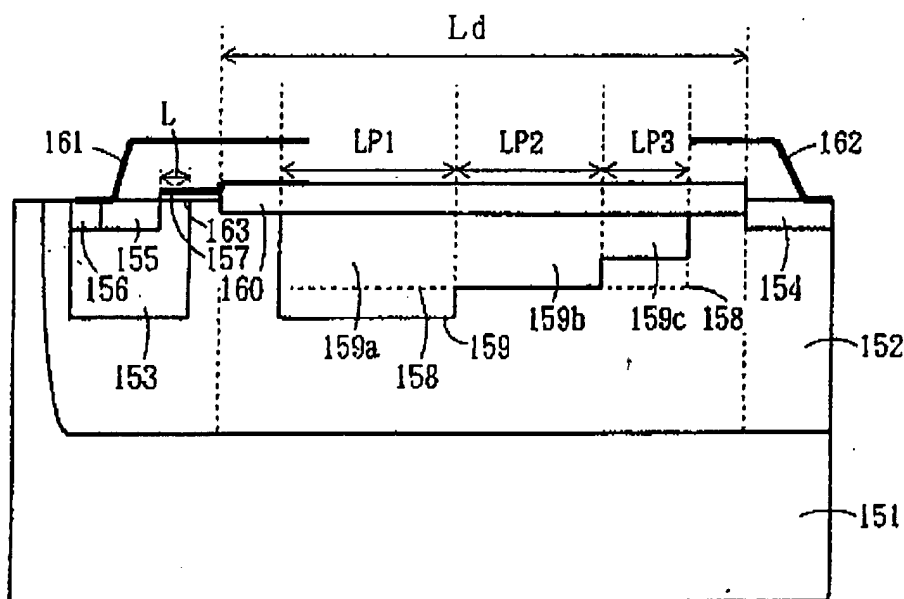


Fig. 12

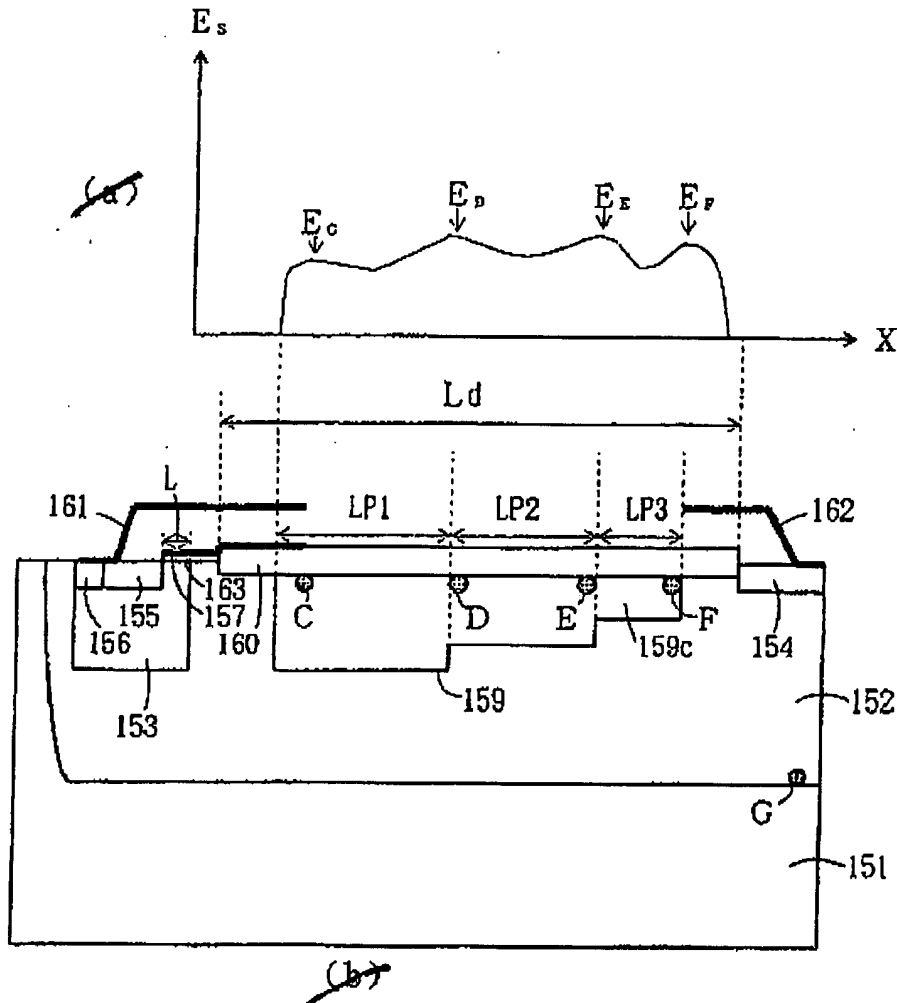


~~5/13~~

Fig. 13



- 151: ~~p type substrate~~
- 152: ~~n type well region~~
- 153: ~~p type base region~~
- 154: ~~n type drain region~~
- 155: ~~n type source region~~
- 156: ~~p type contact region~~
- 157: ~~Gate electrode~~
- 158: ~~Boron diffusion depth~~
- 159: ~~p type diffusion region (p type offset region)~~
- 159a: ~~First p type sub region~~
- 159b: ~~Second p type sub region~~
- 159c: ~~Third p type sub region~~
- 160: ~~Insulation film~~
- 161: ~~Source electrode~~
- 162: ~~Drain electrode~~
- 163: ~~Gate insulation film~~

~~8/13~~
Fig. 14

31/3

Fig. 16(a)

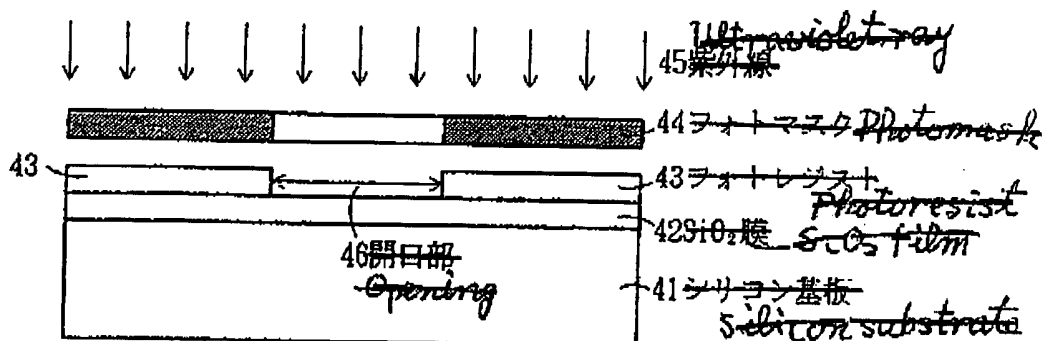


Fig. 16(b)

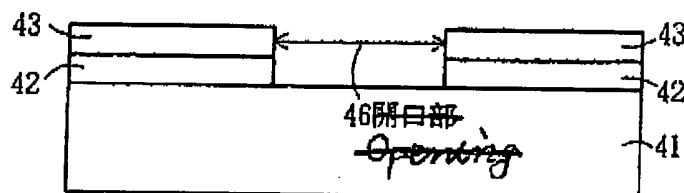


Fig. 16(c)

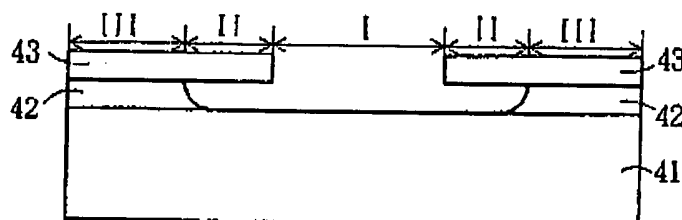


Fig. 16(d)

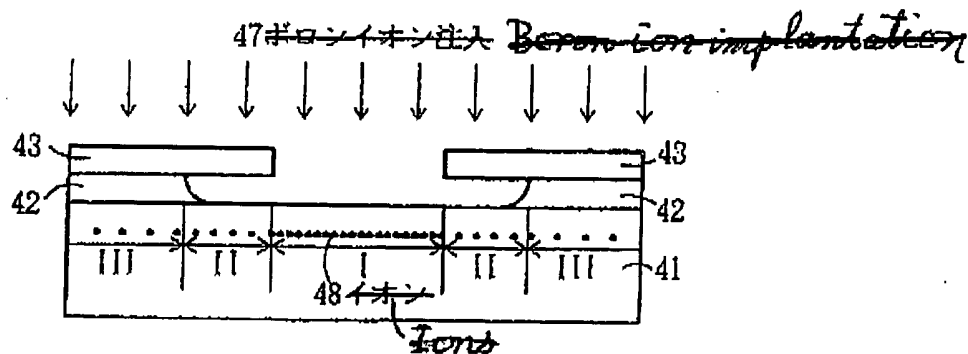
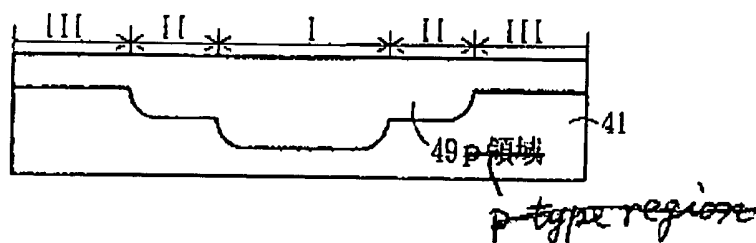
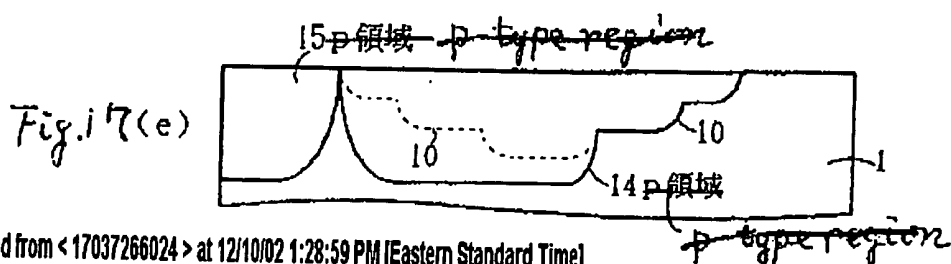
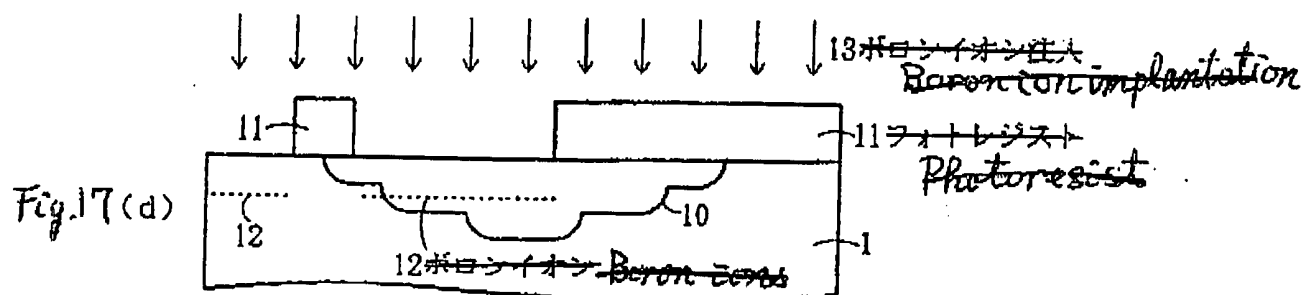
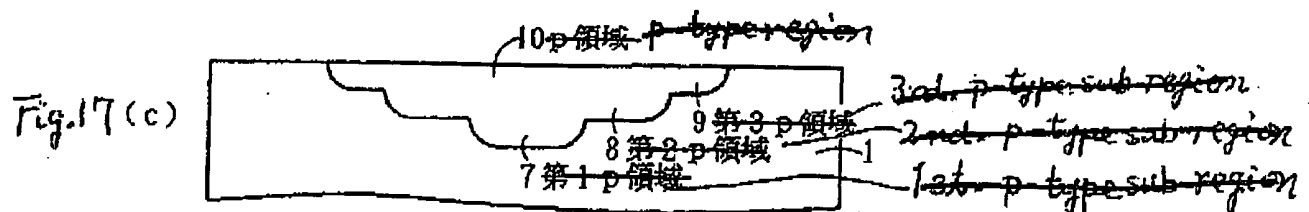
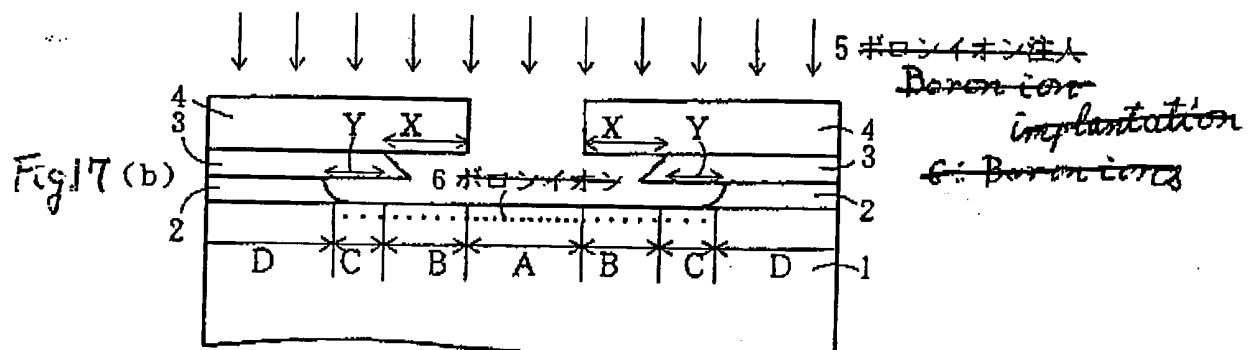
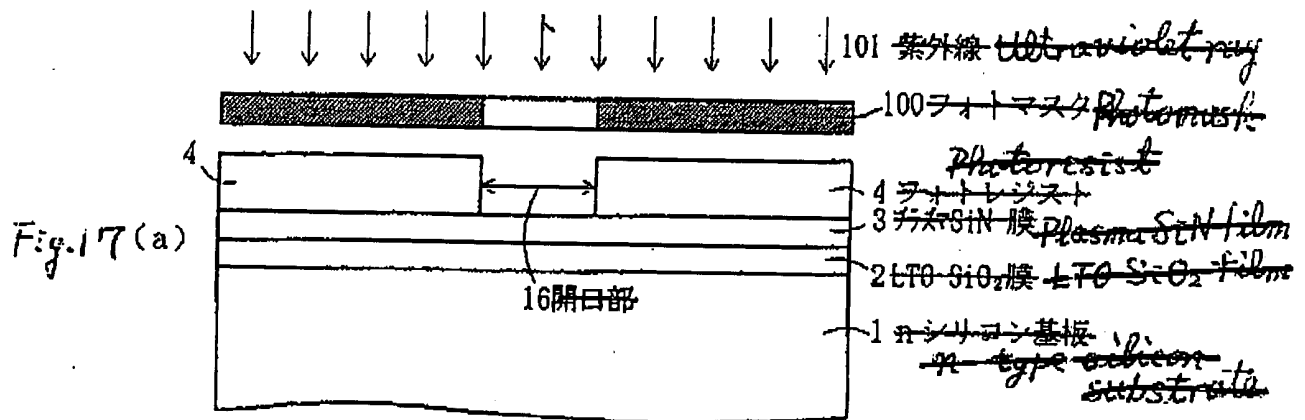


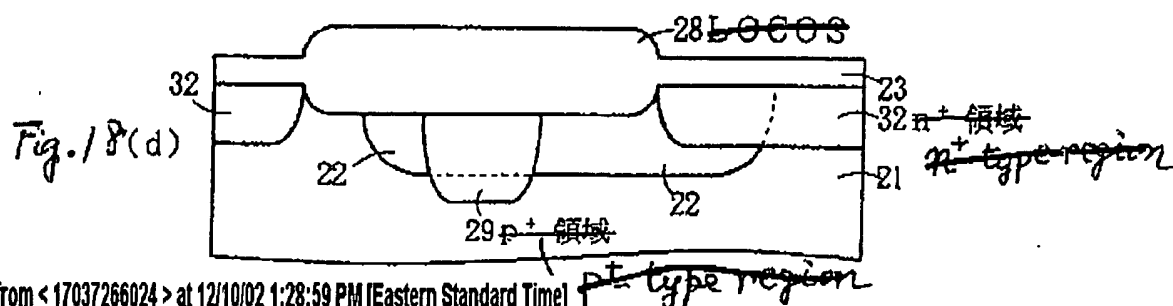
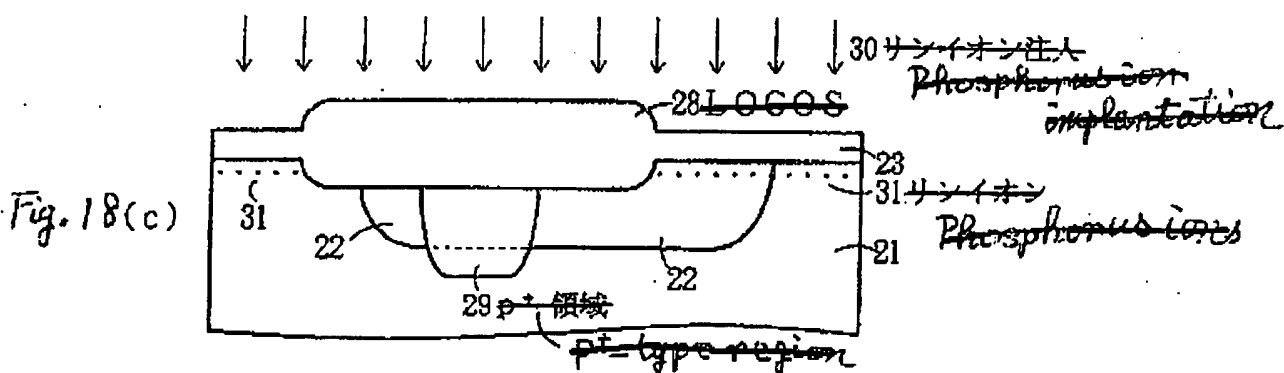
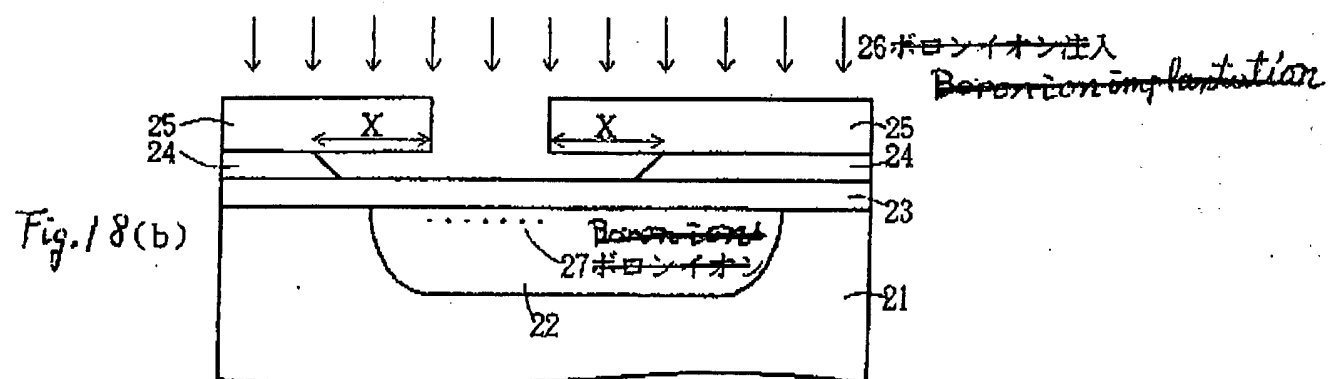
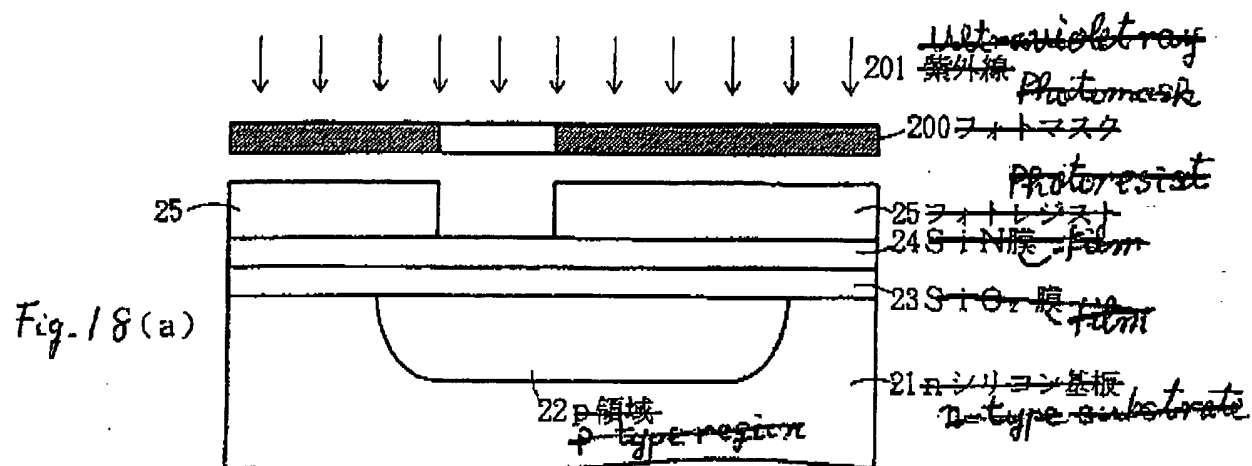
Fig. 16(e)



9/7/9



10/18



4473

Fig-19

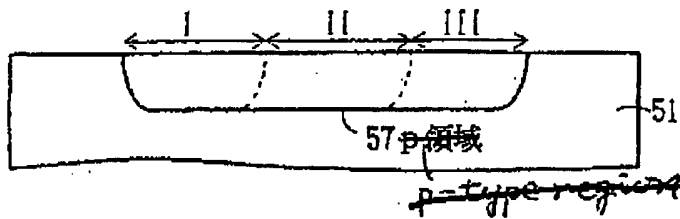


Fig. 20

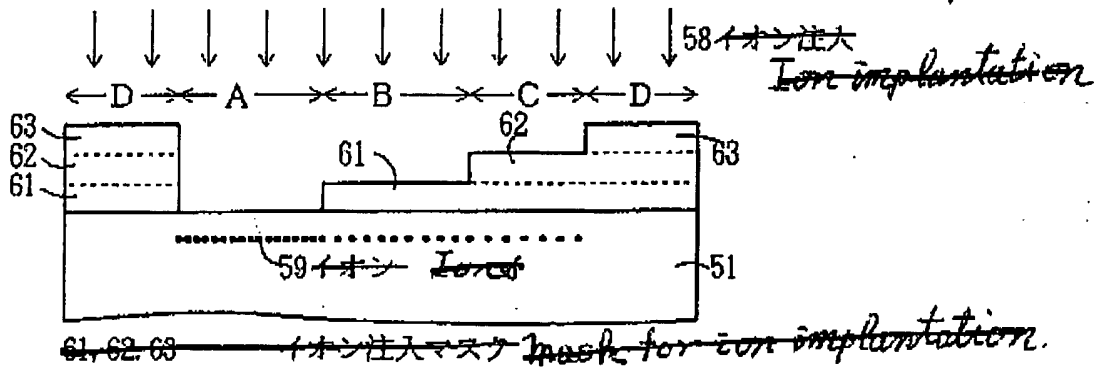
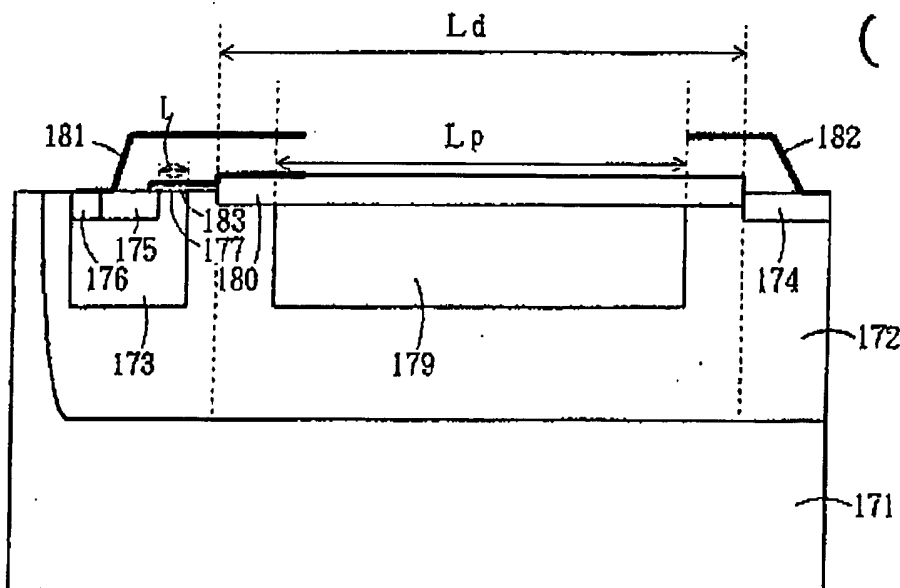
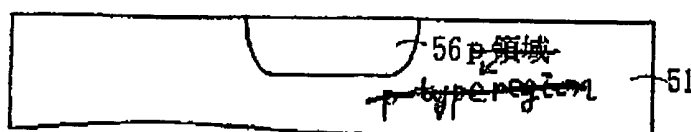
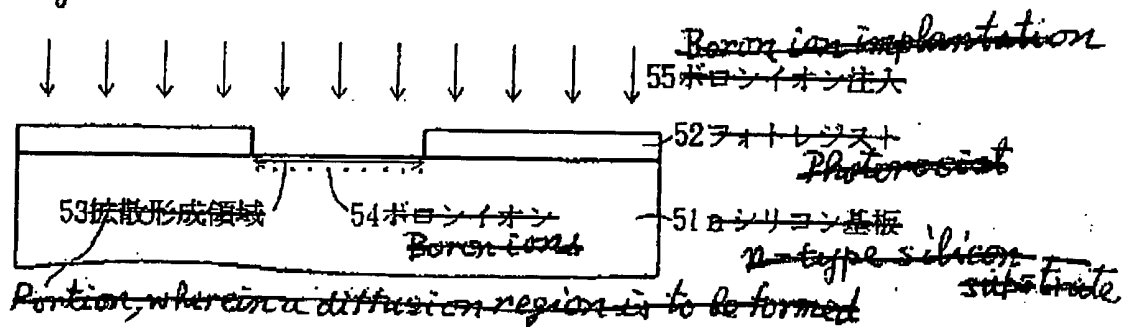
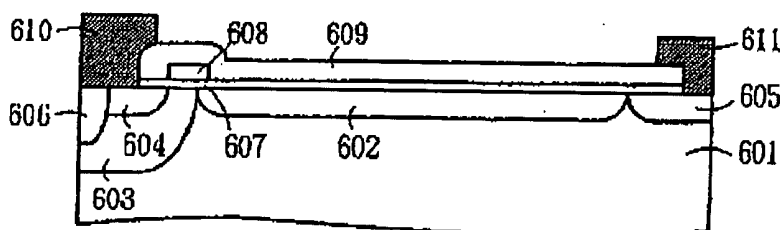


Fig. 21
(Prior Art)



- | | |
|--------------------------------------|--|
| 171: p-type substrate | 177: Gate electrode |
| 172: n-type well region | 179: p-type diffusion region (p-type offset region) |
| 173: p-type base region | 180: Insulation film |
| 174: n-type drain region | 181: Source electrode |
| 175: n-type source region | 182: Drain electrode |
| | 183: Oxide film |

Fig. 22(a) (Prior Art)

Fig. 22(b)
(Prior Art)Fig. 23
(Prior Art)

601: n-type silicon substrate
 602: p-type region (p-type offset region)
 603: p-type region (p-type base region)
 604: n-type source region
 605: n-type drain region
 606: p-type contact region

607: Gate oxide film
 608: Gate electrode
 609: Insulation film
 610: Source electrode
 611: Drain electrode

~~13/13~~

Fig. 24
(Prior Art)

